

# **Final Product Change Notification**

Issue Date: 27-Oct-2019 Effective Date: 24-Jan-2020

Dear Gordon Love,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to <u>view this</u> notification online

This notice is NXP Company Proprietary.

# QUALITY

201909023F01

## **Management Summary**

LPC540xx will be sourced from die revision 1B.

**Change Category** 

Orlange Galegory				
[] Wafer Fab Process	[] Assembly Process	[] Product Marking	[] Test Location	[X] Design
[] Wafer Fab Materials	[] Assembly Materials	[] Mechanical Specification	n[]Test Process	[] Errata
[] Wafer Fab Location	[] Assembly Location	[] Packing/Shipping/Labeling	[] Test Equipment	[] Electrica spec./Test coverage

[] Firmware [] Other

LPC540xx Revision Change from 0A to 1B

# **Description of Change**

Microcontroller products LPC540xx will be sourced from the new product revision 1B to resolve multiple errata items.

Product revision 1B resolves the following errata as described in the device errata sheet, <a href="https://www.nxp.com/docs/en/errata/ES\_LPC540xx.pdf">https://www.nxp.com/docs/en/errata/ES\_LPC540xx.pdf</a>

ISP.1, OTP.1, OTP.2, USB.1, USB.3, IOCON.1, ROM.1 and USB.ROM.1.

## **Reason for Change**

To fix the functional deviations ISP.1, OTP.1, OTP.2 USB.1, USB.3, IOCON.1, ROM.1 and USB.ROM.1 as documented in the errata sheet.

## **Identification of Affected Products**

Top side marking

The last 2 characters of the last line in the top side marking changes from "0A" to "1B"

# **Product Availability**

## Sample Information

Samples are available upon request

#### Production

Planned first shipment 28-Dec-2019

# Anticipated Impact on Form, Fit, Function, Reliability or Quality

No change to form, fit or function other than the fixed errata items

#### **Data Sheet Revision**

No impact to existing datasheet

## **Disposition of Old Products**

Existing inventory will be shipped until depleted

## **Additional information**

Affected products and sales history information: see attached file

Self qualification: view online
Additional documents: view online



## **Timing and Logistics**

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 25-Nov-2019.

# **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Tim Camenzind
Position Quality Manager

e-mail address <u>tim.camenzind@nxp.com</u>

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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